

Applicant: Dong-Ho Lee
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For: STACK PACKAGE MADE OF CHIP SCALE PACKAGES

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FOREIGN PATENT DOCUMENTS

<u>Exam</u>	<u>Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country</u>	<u>Name</u>
	<u>TL</u>	—	JP2000-216327	4/8/2000	Japan	Oda Toshiaki
	<u>IL</u>	—	KR2001-11310	2/15/2001	Korea	Jang and Ko
	<u>PL</u>	—	KR2001-28845	4/6/2001	Korea	Kim and Lee

OTHER DOCUMENTS

<u>Exam</u>	<u>Init</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
	<u>PL</u>	—	English language of Abstract for Japanese Patent Publication No. JP2000-216327, published 4/8/2000.
	<u>IL</u>	—	English language of Abstract for Korean Patent Publication No. KR2001-11310, published 2/15/2001.
	<u>PL</u>	—	English language of Abstract for Korean Patent Publication No. KR2001-28845, published 4/6/2001.

Examiner: 

Date Considered: 04/21/05